

Notice of References Cited	Application/Control No. 10/073,106	Applicant(s)/Patent Under Reexamination YAMAMOTO ET AL.	
	Examiner Paul D. Kim	Art Unit 3729	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-6,209,196	04-2001	Ozono et al.	29/840
	C	US-5,722,160	03-1998	Uemura et al.	29/840
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	K	US-			
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	M	US-			

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	N	JP 57188833 A	11-1982	Japan	KOBAYASHI et al.	H01L 21/58
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.